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IN THE SPECIFICATION

Page 1, lines 11-16 have been amended as follows:

Products that have waterproof, vibration-proof, and/or heat dissipative capabilities are well known. For example, for being waterproof, sealing members or the like are provided in a product. But the prior art is unsatisfactory for the purpose for which the invention is concerned. Thus, continuing improvements in the exploitation of waterproof, vibration-proof, and heat dissipative devices are constantly being sought.

Page 1, lines 18-25 have been amended as follows:

It is an object of the present invention to provide a housing for enclosing an electronic element of an electronic device, comprising a first hole for injecting fluid of nonconductive, non-corrosive, and high heat transfer capability (e.g., silicon oil or hydro oil) or a semisolid substance having similar properties thereinto, a second hole for evacuating air, and two stop members inserted ~~in~~ into the holes for sealing after the injection. By utilizing the present invention, the electronic element is adapted to be waterproof and vibration-proof, and has a predetermined heat dissipation capability.

Page 2, lines 5 and 6 have been amended as follows:

FIG. 1 is a perspective, ~~phantom~~ view of a preferred embodiment of a housing of an electronic element according to the invention.

Page 2, lines 8-23 have been amended as follows:

Referring to FIG. 1, there is shown a parallelepiped housing 3 in accordance with the invention. The housing 3 is mounted on a circuit board 2 of an electronic device (e.g., notebook computer, PDA, cellular phone, or the like). A heat source (e.g., CPU or the like) ~~1-on~~ contacting with the circuit board 2 is the component enclosed by the housing 3. ~~Two data~~ Data lines (or power cords or antennas) ~~11-are extended from~~ of the heat source 1 are extendable through one side of the housing 3. The housing 3 is formed of plastic material (e.g., rubber) without electromagnetic waves shielding capability. The housing 3 comprises a first hole 31 for permitting fluid 4 of nonconductive, non-corrosive, and high heat transfer capability (e.g., silicon oil or hydro oil) or a semisolid substance having similar properties (in other embodiments) to

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~~inject~~ be injected thereinto, and comprises a second hole 32 for permitting air to exit while injecting. Alternatively, ~~evacuate~~ air can be evacuated from the housing 3 to the highest possible degree prior to the injection. ~~Insert-stop~~ Stop members 5 ~~in~~ are inserted into the holes 31 and 32 for sealing after the injection has been finished (i.e., the housing 3 is full of fluid 4). As a result, the electronic element 1 is waterproof and vibration-proof, and has an acceptable heat dissipation capability.